

Amendments to the Specification:

Please replace the title on page 1, line 1 with the following:

SEMICONDUCTOR PACKAGE WITH LEADFRAME INDUCTORS

Please amend the Abstract on page 11 as follows:

A semiconductor device in which an inductance element formed in a resin package has stable characteristics, impedance matching is achieved easily, and the stability of high-frequency characteristics is improved, more particularly a [[A]] semiconductor chip, a mold resin sealing the semiconductor chip, and a plurality of sealed within mold resin having a conductor leads lead extending from an inside of the mold resin to an outside thereof ~~are provided~~. A portion of each the conductor lead arranged inside the mold resin forms an internal terminal portion, and a portion thereof arranged outside the mold resin forms an external terminal portion. An electrode of the semiconductor chip and the internal terminal portion of the conductor lead are connected. ~~The internal terminal portion of at least one of the conductor leads forms an inductance element portion, at least a part of which is narrower than the external terminal portion of the conductor outside the mold resin. An inductance element formed in a resin package has stable characteristics, and the stability of high frequency characteristics improves.~~